



Semiconductor Packaging and Test Market in China 2015-2019

“ Semiconductor Packaging and Test Market in China 2015-2019 ” is the latest addition to MarketResearchReports.Biz industry research reports collection.

About semiconductor packaging and testing

Semiconductor packaging involves casing of materials such as metal, plastic, glass, or ceramic on the

silicon wafer. These casings usually contain one or more semiconductor electronic components. A casing protects the silicon wafer against corrosion and impact, clamps the contact pins or leads used to connect the external circuits to the device, and dissipates heat produced in the device. Though packages are usually made in accordance to industry standards, they meet the specifics of an individual manufacturer.

Wafer testing is executed during the semiconductor device fabrication. This involves the testing of all individual integrated circuits present on the wafer. The individual circuits are tested for functional defects using special test patterns. The testing is carried out using an equipment called a wafer prober or handler. Testing is also carried out using testing methods such as system level tests and burn-in method.

Technavio's analysts forecast the semiconductor packaging and test market in China to grow at a CAGR of 7.05% by revenue over the period 2014-2019.

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Covered in this report

The report covers the present scenario and the growth prospects of the semiconductor packaging and test market in China for 2015-2019 along with a market overview. The market has been segmented and sub-segmented on the following basis:

Technavio's report, Semiconductor Packaging and Test Market in China in 2015-2019, has been prepared based on an in-depth market analysis with inputs from industry experts. The report focuses on the landscape of semiconductor packaging and test market in China market and its opportunities in the coming years. The report includes a discussion of the key vendors operating in this market.

Key vendors

Amkor

ASE

PowerTech

SPIL

Other prominent vendors

ChipMos

Greatek

Huanhong

JCET

Nepes Corporation

SMIC

Tianshui Huatian

Unisem

Key market driver : Growth of semiconductor chip application market

Key market challenge : Short lifecycle of semiconductor devices

Key market trend : Emergence of 3D packaging

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